

**AMENDMENTS TO THE SPECIFICATION**

At page 5, kindly replace the paragraph comprising lines 1-5 with the following new paragraph:

The electroplating is carried out employing a current density of about 5 to 25 mA/cm<sup>2</sup> (milliamp) and preferably about 10 to about 20 mA/cm<sup>2</sup>. The electroplating composition typically contains about 0.02 to about 0.211 M (molar) of a copper salt such as CuSO<sub>4</sub> and about 0.02 to about 0.511 M of a complexing agent such as Na<sub>2</sub>EDTA (sodium salt of ethylene diamine tetraacetic acid).